



Final Product Change Notification

202306009F01 : DIE ATTACH GLUE CHANGE DUE TO HENKEL 8388A DISCONTINUATION

Note: This notice is NXP Company Proprietary.

Issue Date: Sep 22, 2023 **Effective date:** Dec 21, 2023

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Management summary

For all Sales Items of MOA4 and MOA8 modules the used die attached glue Henkel LOCTITE ABLESTIK 8388A will change to Henkel LOCTITE ABLESTIK QMI550.

The existing die attach glue has been discontinued by our supplier in December 2022. NXP could arrange enough die attach glue to be able to produce until December 2023.

From January 2024 onwards the new die attach glue will be used in production after depletion of the existing glue stock.

The new die attach glue has been carefully selected together with Henkel LOCTITE ABLESTIK ABP 2035SCR to enhance the overall performance and durability of the product for qualifications.

Out of qualification Henkel LOCTITE ABLESTIK QMI550 turned out to be the glue of choice to release to production.

Change Category

<input type="checkbox"/> Wafer Fab Process	<input checked="" type="checkbox"/> Assembly Process	<input type="checkbox"/> Product Marking	<input type="checkbox"/> Test Process	<input type="checkbox"/> Design
<input type="checkbox"/> Wafer Fab Materials	<input checked="" type="checkbox"/> Assembly Materials	<input type="checkbox"/> Mechanical Specification	<input type="checkbox"/> Test Equipment	<input type="checkbox"/> Errata
<input type="checkbox"/> Wafer Fab Location	<input type="checkbox"/> Assembly Location	<input type="checkbox"/> Packing/Shipping/Labeling	<input type="checkbox"/> Test Location	<input type="checkbox"/> Electrical spec./Test coverage
<input type="checkbox"/> Firmware	<input type="checkbox"/> Other			

PCN Overview

Description

The die attach glue used between the chip and lead frame in chip on lead frame packaging serves as a bonding material to securely attach the chip to the lead frame. This die attach adhesive is changed from Henkel LOCTITE ABLESTIK 8388A to Henkel LOCTITE ABLESTIK QMI550 for all MOA4 and MOA8 modules.

There are no changes to the form, fit and function of the MOA4 and MOA8 modules due to the changeover to the new die attach glue from the same supplier.

The revised module continues to offer the same high-quality performance and reliability standards.

Attached to this notification, you will find the Qualification Report which outlines the qualification results and criteria for the revised modules.

Reason

The existing die attach glue has been discontinued by our supplier in December 2022. NXP could arrange enough die attach glue to be able to produce until December 2023.

The new qualified die attach glue from Henkel LOCTITE ABLESTIK QMI550 will be used in production after depletion of the existing stock of Henkel LOCTITE ABLESTIK 8388A.

Identification of Affected Products

Product identification does not change

Product Availability

Sample Information

Samples are available upon request

Production

Planned first shipment

Anticipated Impact on Form, Fit, Function, Reliability or Quality

No Impact on form, fit, function, reliability or quality

Data Sheet Revision

No impact to existing datasheet

Disposition of Old Products

Existing inventory will be shipped until depleted

Additional information

Self qualification:[view online](#)

Timing and Logistics

In compliance with JEDEC J-STD-046, your acknowledgement of this change is expected by Oct 22, 2023.

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

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